

CHO-BOND® 584-208

Two Component Electrically Conductive Epoxy Adhesive System

CHO-BOND 584-208 is a two-component, silver filled conductive epoxy adhesive system designed for applications where a strong, highly conductive electrical bond must be achieved. CHO-BOND 584-208 is recommended for applications which require a conductive epoxy with an extended working life such as high volume part dispensing or complex part assembly operations.

Curing of CHO-BOND 584-208 can be achieved in as little as 45 minutes with heat to minimize equipment downtime and increase manufacturing throughput. With a 1:1 weight mix ratio, CHO-BOND 584-208 is easy to handle and use. Typical applications include bonding and grounding of electrical components, cold soldering, and bonding and sealing machined enclosures.



Product Features

- Two component
 - Fast heat cure, increases throughput, minimizes equipment downtime
- Silver filler
 - Good conductivity 0.002 ohm-cm
- Epoxy
 - 60 minute working life, works well over wide temperature range, good chemical resistance >1000 psi lap shear, good for permanently bonding surfaces
- 1:1 Weight mix ratio
 - Easy to weigh out and mix
- Medium paste
 - May be dispensed out of very small needles, fill small cracks and voids. Can be used on overhead or vertical surfaces
- No VOCs
 - Minimal shrinkage, no permits or ventilation required



CHO-BOND® 584-208 PRODUCT INFORMATION

Typical Properties	CHO-BOND 584-208	Test Method	
Polymer	Epoxy	N/A	
Filler	Silver	N/A	
Mix Ratio, A : B (by weight)	1 : 1	N/A	
Color	Silver	N/A	(Q)
Consistency	Medium Paste	N/A	(Q)
Maximum DC Volume Resistivity (Cure Cycle 1)	0.002 ohm-cm	CHO-95-40-5101*	(Q/C)
Minimum Lap Shear Strength (Cure Cycle 1)	1000 psi (6895 kPa)	CHO-95-40-5300*	(Q/C)
Specific Gravity (Room Temp Cure)	2.6	ASTM D792	(Q/C)
Hardness (Cure Cycle 1)	80 Shore D	ASTM-D2240	(Q)
Continuous Use Temperature	- 62°C to 100°C (-80°F to 212°F)	N/A	(Q)
Elevated Temperature Cure Cycle	Cure Cycle Option 1: 0.75 hour @ 100°C (212°F) Cure Cycle Option 2: 2.0 hours @ 65°C (150°F)	N/A	
Room Temperature Cure	24 hours	N/A	(Q)
Working Life	1.0 hours	N/A	(Q)
Shelf Life, unopened	9 months @ 25°C (77°F)	N/A	(Q)
Minimum thickness recommended	0.001 in (0.03 mm)	N/A	
Maximum thickness recommended	None	N/A	
Volatile Organic Content (VOC)	0 g/l	Calculated	
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	10,500 in² (67,742 cm²)	N/A	

Note: N/A – Not Applicable, [Q/C] – Qualification and Conformance Test, [Q] – Qualification Test

* This test Method is available from Parker Chomerics.

CHO-BOND® 584-208 PRODUCT INFORMATION

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 584-208	85	2 component, 4 fluid ounce polypropylene kit	50-00-0584-0208	Not Required
CHO-BOND 584-208	454	2 component, 16 fluid ounce polypropylene kit	50-01-0584-0208	Not Required

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.



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